



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2024-05-20
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32C071CUB6	60MI*493XXXZ	A	998Z	2024-05-20
Amount	Unit of measure	Unit type	ST ECOPACK grade	
102	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	0	
Package designator	Package size	Number of instances	Shape	
QFN	7x7	48	Flat	
Comment	Package : A0B9 UFQFPN 7X7X0.55 48L 0.5 MM PITCH 8202210			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
,		

QueryList : REACH-23rd January 2024				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	0			



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	60MI*493XXXZ		101.5577		600000.0	100000.0				
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or dies	M-011 Other inorganic materials	1.467	mg	supplier	die	Silicon (Si)	7440-21-3		1.338	mg	911738	13170				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.006	mg	4032	58				
				supplier	metallization	Copper (Cu)	7440-50-8		0.055	mg	37634	544				
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.018	mg	12097	175				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	448	6				
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	448	6				
				supplier	Passivation	Silicon Nitride	12033-89-5		0.014	mg	9409	136				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.035	mg	24194	349				
				Glue epoxy (EN4900GC)	Other Organic Materials	0.213	mg	supplier	Organic Compounds	Acrylic resin	Proprietary		0.015	mg	70000	147
								supplier	Organic Compounds	Polybutadiene derivative	Proprietary		0.004	mg	20000	42
supplier	Organic Compounds	Butadiene copolymer	Proprietary						0.003	mg	15000	32				
supplier	Organic Compounds	Acrylate	Proprietary						0.012	mg	54000	114				
supplier	Organic Compounds	Epoxy resin	Proprietary						0.006	mg	30000	63				
supplier	Organic Compounds	Peroxide	Proprietary						0.002	mg	8000	17				
supplier	Organic Compounds	Additive	Proprietary						0.004	mg	18000	38				
supplier	Metals	Silver (Ag)	7440-22-4						0.168	mg	785000	1650				
Encapsulation (EME- G631BQ-CJ)	Other Organic Materials	37.371	mg	supplier	Organic Compounds	Epoxy Resin A	Proprietary		2.055	mg	55000	20239				
				supplier	Organic Compounds	Epoxy Resin B	Proprietary		0.785	mg	21000	7728				
				supplier	Organic Compounds	Phenol Resin	Proprietary		2.055	mg	55000	20239				
				supplier	Glass	Silica(Amorphous)A	60676-86-0		28.738	mg	769000	282976				
				supplier	Glass	Silica(Amorphous)B	7631-86-9		2.803	mg	75000	27598				
				supplier	Organic Compounds	Metal Hydroxide	Proprietary		0.747	mg	20000	7360				
				supplier	Organic Compounds	Carbon Black	1333-86-4		0.187	mg	5000	1840				
Bonding wire (Cu)	Bonding Wire	0.428	mg	supplier	Metals	Copper (Cu)	7440-50-8		0.413	mg	965500	4066				
				supplier	Metals	Palladium (Pd)	7440-05-3		0.013	mg	31000	131				
				supplier	Metals	Gold (Au)	7440-57-5		0.001	mg	3500	15				
Plating anode (Sn)	Other inorganic materials	1.078	mg	supplier	Metals	Tin (Sn)	7440-31-5		1.078	mg	1000000	10619				
Leadframe (C7025 + Ag)	Copper & its alloys	61.000	mg	supplier	Metals	Copper (Cu)	7440-50-8		55.946	mg	917140	550874				
				supplier	Metals	Nickel (Ni)	7440-02-0		1.373	mg	22500	13514				
				supplier	Metals	Silicon (Si)	7440-21-3		0.159	mg	2600	1562				
				supplier	Metals	Magnesium (Mg)	7439-95-4		0.070	mg	1150	691				
				supplier	Metals	Silver (Ag)	7440-22-4		3.453	mg	56610	34002				